



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Hsieh et al.  Serial No.: 10/052,989	) Art Unit: 2818	, oanta 800
	) Examiner: David Vu	t to the state of
	)	
Filing Date: November 9, 2001	)	
For: Formation of Electroplate	)	
Solder on an Organic Circuit	)	
Board for Flip Chip Joints and	)	
Board to Board Solder Joints	)	
	)	

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## AMENDMENT TO OFFICE ACTION DATED APRIL 11, 2003

In response to the Office Action dated April 11, 2003, the time for response being extended to August 11, 2003 by the attached Petition for Extension of Time, please enter and consider the following amendments and remarks: